

FENG-JUI TECHNOLOGY CO., LTD

PIC201610LDQ1 TYPE

● FEATURE

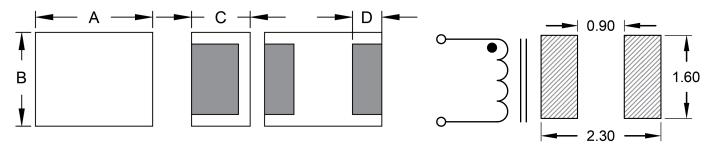
- 1. Shielded construction(height=1.00mm Max.)
- 2. Frequency range up to 5MHz, Low DCR(Ω)
- 3. AEC-Q200 Qualified

Applications

1. Notebook, server application, High current power supplier

Shape and Dimension

Schematics and Land Patterns(mm)



A=2.0±0.2mm; B=1.6±0.2mm; C=1.00mm Max.; D=0.5±0.3mm

Specification

P/N	L (µH)	RDC	Isat (A)		Irms (A)	
		(mΩ) Max.	Тур.	Max.	Тур.	Max.
PIC201610LDQ1-R10M	0.10±20%	12.0	9.0	8.1	6.0	5.4
PIC201610LDQ1-R24M	0.24±20%	20.0	6.8	6.3	5.8	5.3
PIC201610LDQ1-R33M	0.33±20%	27.0	6.6	6.2	4.6	4.1
PIC201610LDQ1-R47M	0.47±20%	29.0	6.0	5.4	4.4	4.1
PIC201610LDQ1-1R0M	1.0±20%	65.0	3.8	3.4	3.3	3.1
PIC201610LDQ1-1R5M	1.5±20%	97.0	3.5	3.2	2.5	2.3
PIC201610LDQ1-2R2M	2.2±20%	140.0	2.7	2.5	2.3	2.1
PIC201610LDQ1-4R7M	4.70±20%	288.0	1.8	1.6	1.3	1.1

Note1. Measurement frequency of Inductance value: at 1MHz, 1V

Note3. Isat: DC current at which the inductance drops 30%(Typ.) from its value without current

Note4. Irms: Average current for 40° C temperature rise from 25° C ambient(Typ.)

Note5. Packaging: Taping; Quantity: 3000 Pieces/Reel



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GENERAL CHARACTERISTICS

- 1. Operating temperature range: -40 TO + 125°C (Includes temperature when the coil is heated)
- 2. High temperature exposure(storage) refer MIL-STD-202 Method 108: 1000 hrs at rated operating temperature(e.g. 125°ℂ). Part can be stored for 1000 hrs @125°ℂ. Unpowered. Measurement at 24±4 hours after test conclusion.
- 3. Temperature cycling refer JESD22 Method JA-104: 1000 cycles(-40 TO + 125℃). Measurement at 24±4 hours after test conclusion. 30 min maximum dwell time at each temp. extreme. 1 min. maximum transition time.
- 4. Biased Humidity refer MIL-STD-202 Method 103: 1000 hours 85℃/85%RH. Unpowered. Measurement at 24±4 hours after test conclusion.
- 5. Operational Life refer MIL-PRF-27: 1000 hrs. at 125 °C tested. Measurement at 24±4 hours after test conclusion.
- 6. External Visual refer MIL-STD-883 Method 2009: Inspect device construction, marking and workmanship.
- 7. Physical Dimension refer JESD22 Method JB-100: Verify physical dimensions to the applicable device detail specification.
- 8. Resistance to Solvents refer MIL-STD-202 Method 215: Add aqueous wash chemical OKEM clean or equivalent.
- 9. Mechanical Shock refer MIL-STD-202 Method 213: Figure 1 of Method 213. Condition C.
- 10. Vibration refer MIL-STD-202 Method 204: 5g;s for 20 minutes, 12 cycles each of 3 orientations. Test from 10-2000 Hz.
- 11. Resistance to soldering Heat refer MIL-STD-202 Method 210: Condition B No pre-heat of samples. Single wave solder-procedure 2 for SMD and procedure 1 for leaded with solder within 1.5mm of device body.
- 12. ESD refer AEC-Q200-002 or ISO/DIS 10605: Direct contact discharge 2kV.
- 13. Solderability refer J-STD-002: For both Leaded & SMD. Magnification 50X. Conditions: Leaded, Method A@235℃,category 3; SMD, a)Method B, 4hrs@125℃ dry heat @235℃, b)Method B@215℃ category 3., c)Method D category 3@260℃
- 14. Electrical Characterization refer spec: Show Min, Max Mean and Standard deviation at room from Min and Max temperature.
- 15. Flammability refer UL-94: V-0 or V-1 Acceptable.
- 16. Board Flex refer AEC-Q200-005: 60 sec minimum holding time.
- 17. Terminal Strength(SMD) refer AEC-Q200-006
- 18. Reflow profile recommend:

